Texas Instruments Inc. (DUNS# 00-732-1904) Supplier Name:

Contact Info:

ti.com/support
Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

05/06/2022

## Details for "TLC071CDR"

### **Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TLC071CDR	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D   8	3.91x4.9x1.58	84.5

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

### **Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB	
Yes	Yes	Yes	Yes	

## **Component Information**

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.039738	99.989935	999899	0.047038	470
Not Categorized	Proprietary Materials		0.000003	0.007549	75	0.000004	0
Precious Metals	Silver	7440-22-4	0.000001	0.002516	25	0.000001	0
Sub-Total			0.039742	100	1000000	0.047043	470
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.190013	80.000084	800001	0.224919	2249
Thermoplastics	Epoxy	85954-11-6	0.047503	19.999916	199999	0.056229	562
Sub-Total			0.237516	100	1000000	0.281148	2811
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	24.416166	97.425006	974250	28.901496	289015
Copper and Its Alloys	Iron	7439-89-6	0.601476	2.4	24000	0.711969	7120
Copper and Its Alloys	Phosphorus	7723-14-0	0.003759	0.014999	150	0.00445	44
Copper and Its Alloys	Tin	7440-31-5	0.007518	0.029998	300	0.008899	89
Copper and Its Alloys	Zinc	7440-66-6	0.025061	0.099998	1000	0.029665	297
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.007518	0.029998	300	0.008899	89
Sub-Total			25.061498	100	1000000	29.665377	296654
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.036621	95.121951	951220	0.043348	433
Precious Metals	Gold	7440-57-5	0.0003	0.779241	7792	0.000355	4
Precious Metals	Palladium	7440-05-3	0.001578	4.098808	40988	0.001868	19
Sub-Total			0.038499	100	1000000	0.045571	456
Mold Compound	•	*	•	-	•	•	
Other Inorganic Materials	Fused Silica	60676-86-0	51.327665	88	880000	60.756725	607567
Other Plastics and Rubber	Carbon Black	1333-86-4	0.174981	0.300001	3000	0.207126	2071
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.320798	0.55	5500	0.37973	3797
Thermoplastics	Ероху	85954-11-6	6.503448	11.149999	111500	7.698153	76982
Sub-Total			58.326892	100	1000000	69.041733	690417
Semiconductor Device	•				•	•	
Ceramics / Glass	Doped Silicon	7440-21-3	0.776484	100	1000000	0.919127	9191
Sub-Total			0.776484	100	1000000	0.919127	9191
Total			84.480631			100	1000000

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

## See Glossary of Terms for more details.

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

# **Product Content Methodology**

For an explanation of the methods used to determine material weights, See Product Content Methodology

## Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

# Important Information/Disclaimer

Tibases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Tl and Tl suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by Tl. The material content information is

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/06/2022

ROHS: Means TI semiconductor products that are compliant with the current ROHS requirement that the maximum concentration values of the ten substances listed in ROHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szzq088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (5b203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.